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#4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Edgar R. Zuniga-Ortiz, et al.

Art Unit: TBD

Serial No.: 10/057,138

Examiner: TBD

Filed: 01/25/02

Docket: TI-33986

For: Flip-Chip Without Bumps and Polymer for Board Assembly

4 / 4amal
Drawings
E. Willis
10-4-02

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 4-10-02
as First Class Mail in an envelope addressed to: Assistant
Commissioner for Patents, Washington, D.C. 20231.

Karen Vertz
Karen Vertz

4-10-02
Date

Assistant Commissioner for
Patents
Washington, D. C. 20231

Dear Sir:

Enclosed are **FOUR (4)** sheets of formal drawings for the above-referenced case.
Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments
Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated
P.O. Box 655474 M/S 3999
Dallas, Texas 75265
(214) 939-8651

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Reg. No. 20,250
Attorney for Applicants